semiconductor packaging news

YES Joins Forces with EV Group – April 22, 2021

semiconductor packaging news

We search for industry news, so you don't need to.

Gel-Pak & BAE Collaborate on Product
Gel-Pak's Lid/Clip Super System (LCS2™) was developed with BAE Systems to protect thin components from migrating out of pockets of waffle pack chip trays.

Gel-Pak, a Division of Delphon

April 22, 2021

TSMC's Founder Calls on Taiwan to Defend Its Chip Industry
Morris Chang, the founder and former chairman of the world's most valuable chip company, has called on Taiwan and its government to defend the island's semiconductor manufacturing leadership amid a push by the U.S. and China to build up their own chipmaking capabilities. Chang, who established Taiwan Semiconductor Manufacturing Co. in 1987, is seen as the founding father ...
Nikkei Asia

SiP Printing of the Future
Welco®AP5112 Type 7 paste enables the single-step printing process for both flip-chip & passive component attach, which significantly reduces assembly cost and solder defects.

Heraeus Advanced Packaging

Touch Free BGA Solder Ball Removal
Watch a video that shows touch-free BGA component deballing. This precision process is highly reliable when preparing BGA components prior to reballing.

Circuit Technology Center

ASML sales up 30% thanks to chip shortage
ASML Holding NV has sharpened its full-year guidance as demand for its chipmaking equipment has soared during the global semiconductor shortage. The Dutch company ...
Taipei Times

Side Wettable Flanks for Leadless Automotive Packaging
Amkor's Wettable Flank technology for QFN (MLF®) packages streamlines solder joint inspection, enabling automotive and PCB assemblers to eliminate manual and X-ray ...
Technical Paper

Component shortage could last through 2022
Business tycoons said that component shortages might persist through next year due mainly to lingering demand-supply imbalances and chaos in the shipping ...
Taipei Times

Today's Sponsor

Gel-Pak®
Protecting the World's Valuable Devices

Test Your Knowledge
Which of the following is not an acronym? RADAR, RADIO, SCUBA, or LASER
See answer below.

Double sided monolithic lens fabrication
Capability of SUSS UV-imprint lithography with an optically tailored, UV-curable epoxy resin from DELO to manufacture double-sided monolithic wafer-level optics. Read more.

SUSS MicroTec

Press Releases

YES Joins Forces with EV Group
Yield Engineering Systems, Inc. announced it is working with EV Group and will install a YES EcoCoat monolayer coating system at EVG's NILPhotonics® Competence Center ...
Yield Engineering Systems, Inc.

Flashbond UV-3610 UV cured Glob Top
epoxySet introduces the Flashbond UV-3610. This highly unique epoxy chemistry was designed as a glob top encapsulant that can be cured rapidly

Technical Papers

- Die-to-wafer Bonding Accelerates Heterogeneous Integration (HI)
- Advantages of Outsourced Test Services
- Semiconductor Device Innovation Driving Automotive Advances
- Non-Surface Contact Approach For Device Flip
- BGA Socket Considerations - Prototype to Reality
- EMI Shielding for System in Package Using Spray Coating and Silver Particle-Free Ink
- Improved Wire Bond Reliability with Auxiliary Wires

Choices of Dynastrip® Removers

Dynastrip® series offers long bath-life and reduced cost-of-ownership. Each are uniquely formulated photo-resist removers designed specifically for any need. Learn more.
EMD Electronics

Advantages of Outsourced Test Services

Outsourced test services continue to grow as a turnkey service strengthening supply chain management for customers. Read more.
Amkor Technology, Inc.

Amazon's New Quantum Computer Design Relies On Tiny Schrödinger's Cats

Schrödinger's cat is a thought experiment in which a quantum event suspends a cat in a box in a nebulous state between life and death: the cat only definitely ...
IEEE Spectrum

Tapping Into Non-Volatile Logic

Research is underway to develop a new type of logic device, called non-volatile logic (NVL), based on ferroelectric FETs. FeFETs have been a topic of high interest at recent ...
Semiconductor Engineering

PC component shortage to start easing in 2Q22, says Foxconn chairman

Shortages of PC components should start easing in the second quarter of 2022, according to Young-Way Liu, chairman for Foxconn Electronics (Hon Hai). Liu also pointed ...
Digitimes

Trymax
Plasma Technology Solutions for
Wafer Bumping
Advanced Packaging
PR, PI, PBO Descum

LEADER in No-Clean Flip-Chip Flux
NC-26S
INDIUM CORPORATION

SST Vacuum Reflow Systems
Void-Free Soldering
SST 5100 Vacuum Pressure Furnace
Learn More

Bain Considering Bid to Take Toshiba Private, Reuters Says

Bain Capital is exploring a bid to acquire Toshiba Corp., Reuters reported, citing people familiar with the matter. The private equity giant has entered into discussions ...
Bloomberg

Nanya to defend market share with new chip plant, says president

Nanya Technology holds an around 3% share of the DRAM market, and is striving to defend its global market share with an additional 12-inch wafer fab set to come ...
Digitimes

Taiwan's Worst Drought in Decades Deepens Chip Shortage Jitters

In the foothills of Taiwan's mountainous spine, reservoirs are running dry as the island experiences its worst drought in decades -- a crisis that risks deepening an already ...
Industry Week

under 365 LED light. This state-of-the-art ...
EpoxySet Inc.

'Velektronik' research project creates platform for trusted electronics

In order to use electronic devices securely and reliably, it is important to know where they were manufactured, how they operate and how they are constructed. Although ...
Fraunhofer IPMS

Bondtesting of Memory Devices

Bondtesting memory devices means dealing with overhanging and stacked die. Nordson DAGE have a patented test method to ensure no false results are measured.
Nordson DAGE

Quote of the Day

"You only have to do a very few things right in your life so long as you don't do too many things wrong."
Warren Buffett

Bondtesting of Memory Devices

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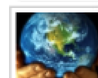
Nordson DAGE

NEW WX3000™ Metrology & Inspection Systems

Increase throughput with the NanoResolution MRS Sensor that is 2-3X faster, delivering greater than 25 wafers (300mm) per hour. Learn more.
Cyberoptics Corporation

What Year Was It?

The First Earth Day



Earth Day, an event to increase public awareness of the world's environmental problems, is celebrated in the United States for the first time.

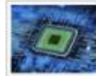
The day was Apr 22. What year was it?

SilcoTek CVD coatings change the game

SilcoTek CVD Coatings are used throughout the semiconductor fabrication world to fight corrosion and metal ion contamination. Learn more by visiting our website.
SilcoTek® Corporation

Die-to-wafer Bonding Accelerates Heterogeneous Integration

Flexible hybrid bonding technologies are key to speeding up the deployment of HI. This white paper reviews different D2W bonding approaches.
EV Group

High-performance IC Packaging

By combining the functionality of a complete system into one packaged device, a SiP solution offers reductions in size, weight and power that are critical to next-generation performance.
Integra Technologies

New Release of Cheetah & Cougar EVO

The next level of x-ray and CT inspection in Semicon - offering optimized automated processes and enhanced resolution. Learn what the systems can do for you!
YXLON

[Rare Earth Mining: The Dark Underside of Sustainability]
Sustainability is not without its challenges for implementors and environmentalists. Think back several years to the paper or plastic debate. Paper bags were causing ...
3DInCites

HOW DO YOU USE A STAKING COMPOUND ON A CIRCUIT BOARD?
ONE PART EPOXY EP17HTDA-1
WATCH VIDEO
MASTERBOND
www.masterbond.com

The Virtual Premier Packaging & Assembly Conference
ECTC
The 2021 IEEE 71st Electronic Components and Technology Conference
June 1 – July 4
REGISTER NOW!
www.ectc.net

Nikon
Delivering Real-world Solutions
Learn about the Nikon NSR-S635E immersion scanner and the inline Alignment Station today!

Cartoon of the Day

"How come you never bring me any of your stupid ideas anymore?"

Copyright © Randy Glasbergen

Have you seen wafer wands without hoses?

Our PORTA-VAC and PORTA-WAND wafer wands eliminate vacuum lines. Rechargeable wands and alkaline battery powered tools are available.
Virtual Industries, Inc.

Test Your Knowledge Answer
Which of the following is not an acronym? RADAR, RADIO, SCUBA, or LASER
Answer: Radio. RADAR (RAdio Detection And Ranging), SCUBA (Self-Contained Underwater Breathing), LASER (Light Amplification by Stimulated Emission of Radiation)

Calendar

- Apr 26, 2021: Advanced CMOS/FinFET Fabrication Webinar
- Apr 26, 2021: 2021 Technology Crossover Extravaganza: CICMT | HiTEC | APEPS
- Apr 27, 2021: VIRTUAL: Microwave Packaging Technology
- Apr 27, 2021: FREE Webinar - DI-Water vs. Chemistry

Die-to-wafer Bonding Accelerates Heterogeneous Integration

Flexible hybrid bonding technologies are key to speeding up the deployment of HI. This white paper reviews different D2W bonding approaches.
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High-performance IC Packaging

By combining the functionality of a complete system into one packaged device, a SiP solution offers reductions in size, weight and power that are critical to next-generation performance.
Integra Technologies

Circuitnet Media, LLC
6 Liberty Square #2040, Boston MA 02109 USA

Jeff Ferry, Publisher | Ken Cavallaro, Editor/Business Manager

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